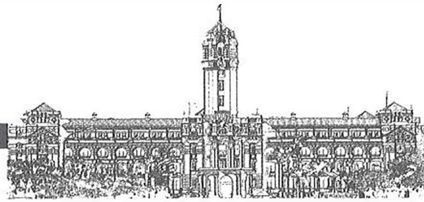

INTELLECTUAL PROPERTY OFFICE
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REPUBLIC OF CHINA

Certificate

The Patent entitled : **HALF-CHIP PACKAGING STRUCTURE**

has been granted according to the Patent Law of the Republic of China.

The followings are the relevant references:

Patentee(s) : **CHENMKO ENTERPRISE CO., LTD**

Inventor(s) : **LIAO, HUANG-SHUN**

Patent Number : **Utility Model No. M641462**

Term of Patent : **From May 21, 2023 to Jan. 15, 2033**

This certificate is only for general reference, when legal matter is involved, the original Chinese document shall be referred.

Liao, Cheng-wei

Liao, Cheng-wei
Director General
Date: Jun. 7, 2023